

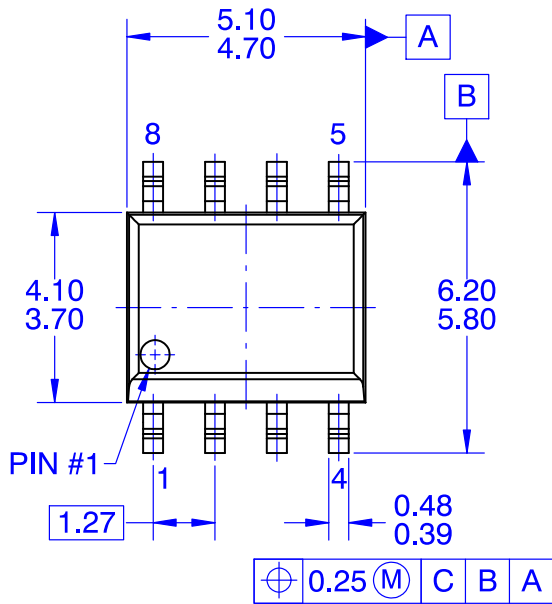
**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

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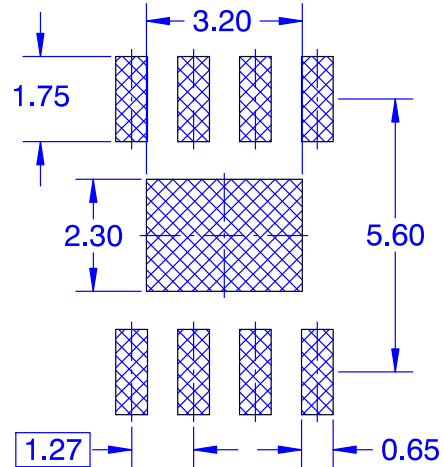


**SOIC8 N EP**  
**CASE 751EJ**  
**ISSUE O**

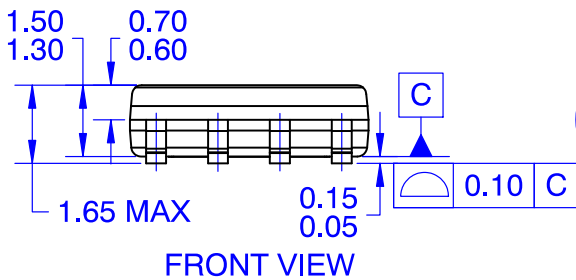
DATE 30 SEP 2016



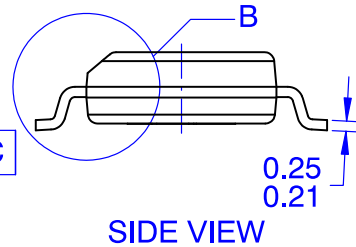
TOP VIEW



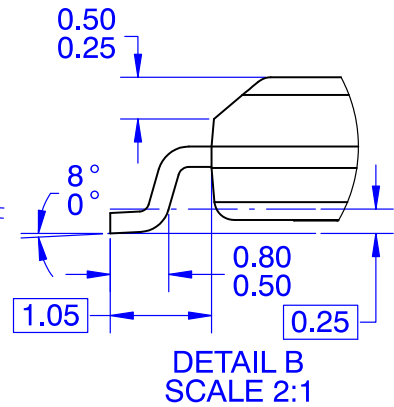
LAND PATTERN RECOMMENDATION



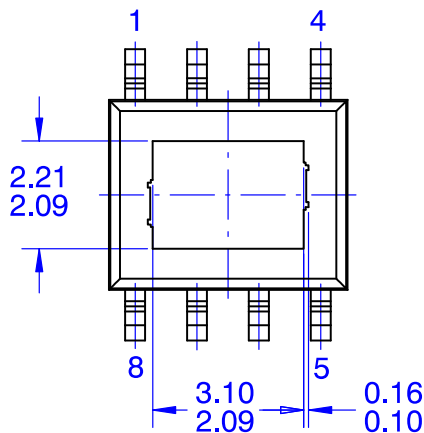
FRONT VIEW



SIDE VIEW



DETAIL B  
SCALE 2:1



BOTTOM VIEW

**NOTES:**

- A. NO INDUSTRY STANDARD APPLIES TO THIS PACKAGE
- B. ALL DIMENSIONS ARE IN MILLIMETERS
- C. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS

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